

# キュア工程での加圧フリー熱伝導接着

Pressure-free in curing process -- Thermal Conductive Adhesive

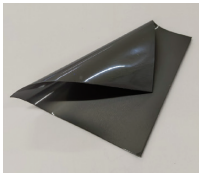
## コンセプト Concept

- ▶ 被着体の凹凸に追従して熱抵抗を低減  
Conform to the surface irregularities of the adhered surface and reduce thermal resistance
- ▶ 貼合後の厚み均一性を向上  
Improve thickness uniformity after lamination
- ▶ ポンプアウトや液だれがなく、良好な作業性  
Good workability without pumping out or liquid dripping

### 低弾性タイプ(開発品)

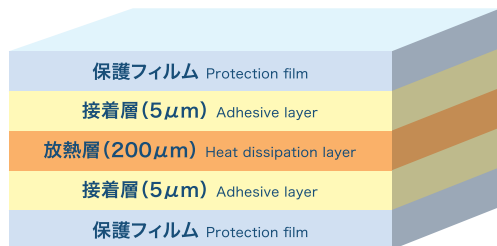
Low Elasticity Type (Development product)

- ▶ 優れた応力緩和性  
Excellent stress relaxation property  
弾性率: 0.42 Gpa  
Elastic Modulus



- ▶ 線膨張係数の異なる材料を貼合  
Bonding materials with different linear expansion coefficient

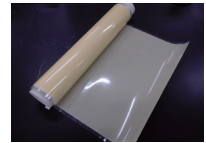
- ▶ 熱伝導率2W/mK(定常法)  
Thermal Conductivity (Steady State Method)



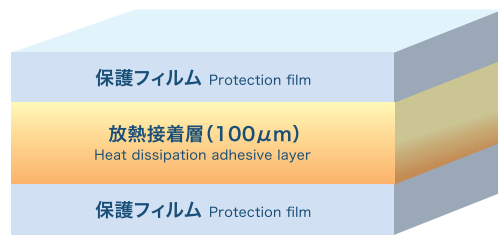
### 高絶縁性タイプ

High Insulation Type

- ▶ AC65kV/mmの電気絶縁性  
(150°C1000h後も特性維持)  
Electrical Insulation: AC65kV/mm  
(No change after 150°C1000h)



- ▶ 熱伝導率2W/mK(定常法)  
Thermal Conductivity  
(Steady State Method)



※放熱層の厚みは調整可能です  
The thickness of the heat dissipation layer is adjustable.

※上記数値は代表値であり保証値ではありません。The data are references, not guaranteed values.

## アプリケーション Application

- ▶ 各種装置部品の接合  
Bonding of various equipment parts
- ▶ 車載用などのパワーデバイス  
Power devices for automobiles, etc.

